**Etan Bennett**

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**Education: Stevens Institute of Technology,** Hoboken, New Jersey

Master of Engineering in Systems Engineering, 2016 GPA: 3.5

Bachelor of Engineering in Electrical Engineering, 2016 GPA: 3.7

**Honors:** E.A. Stevens Scholarship, Presidential Scholarship, D. Performing Arts Scholarship, Dean’s List, President’s List

**Coursework:** Wireless Systems, Autonomous Mobile Robots, Project Management of Complex Systems, System Supportability and Logistics

**Skills: Hardware:** PC based systems, PLCs, Rockwell Systems, Basic Linux, TI Embedded Development, Basic MacOS

National Instruments PCI-Frame Grabber, VPX Development

**Software:** C/C++, LabVIEW, MatLab, RSLogix 5000, SolidWorks, Autodesk AutoCAD, Minitab, Cadence: PSpice/OrCAD/Allegro, ROS Hydro, Altium, Multisim, DOORs

**Lab:** Oscilloscope circuit analysis, dynamic signal analysis, digital multimeter, optical microscopy, soldering, woodworking, metalworking, wiring, short circuit troubleshooting, scanning electron and focused ion beam microscopy, laser scanning microscopy, thermography, spectrum analyzer signal analysis

**Background: Harris Corporation: Electronic Systems,** Clifton, New Jersey

Electronic Warfare Systems Engineer: August, 2016 – Present, 2017

* Supporting EW group with requirements generation
* Collaborating with integration team during RF hardware upgrades
* Assembling VPX hardware
* Developing LabVIEW integration and test software

**Getinge Group: Maquet Cardiopulmonary,** Rastatt, Germany

Co-op Hardware Design: June-December, 2015

* Developed a Bluetooth Low Energy auxiliary sensor device for a life support system
* Documented the design process including: Functional Requirements, Risk Analysis, and HW Specification
* Prototyped the functional HW design to integrate SW architecture and communications concurrently
* Designed PCB Layout for Prototyping
* Resolved PCB malfunction through circuit analysis

**The Aerospace Corporation: Electronic Materials and Devices,** El Segundo, California

Co-op Failure Analysis: May – August, 2014

* Expanded methods to measure the electrical properties of devices and nanoscale materials
* Refined LSM tile scanning procedure to fully image devices at 100x resolution
* Coded lock-in thermography of device defects with LabVIEW, using an infrared imaging camera

**Getinge Group: Maquet Cardiac Assist,** Mahwah, New Jersey

Co-op PCBA Testing: January – May, 2014

* Assisted Electrical Engineers with the testing and documentation of printed circuit board assemblies
* Constructed and tested PCB breadboards to test system sensor modules
* Assembled system test devices for use in product verification
* Wrote engineering specifications and manufacturing functionality test documents

**General Motors: GM Component Holdings LLC,** Rochester, New York

Co-op Quality Process: September – December, 2012

* Created an Excel macro to facilitate collection and analysis of test stand data
* Managed lot traceability and quality documents for management to understand part rejection
* Reviewed machine operation to certify that requested functions met plant qualifications

Co-op Electrical Controls: May – August, 2012

* Supported Gen V Fuel Injector line installation and operation
* Standardized touchscreen interfaces to promote operator ease of use
* Programmed guard door, reject tray and conveyor operation using ladder logic
* Analyzed online code to clarify machine faults and continue production

**Activities:** Volleyball, knitting, sailing, biking, pole vaulting, jazz saxophone, travel, Sigma Nu International Fraternity